

# Bill of Materials

TI DESIGNS  
 Part #: PMP6638  
 Literature #

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	MANUFACTURER	PART NUMBER	SIZE
C1, C2, C14, C16, C28, C30, C43	7	10uF	Capacitor, Ceramic, 25V, -20%, +80%, -33 ~ 85 C	Std	Std	3216
C11, C13, C21, C27, C36, C42, C49	7	1uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C12	1	0.033uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C23	1	68 pF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C24	1	0.012uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C3, C4, C15, C22, C29, C37, C44	7	0.1uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C31, C50	2	Open	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C32, C45	2	100 pF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C38	1	33 pF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C39	1	1000pF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C5, C7, C17	3	15 pF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
C6, C9, C10, C19, C20, C25, C26, C34, C35, C40, C41, C47, C48	13	22uF	Capacitor, Ceramic, 6.3V, 20%, -55 ~ 85 C	TDK	C3216X5R0J226K	3216
C8, C18, C33, C46	4	0.039uF	Capacitor, Ceramic, Low Inductance, vvV, [temp], [tol]	muRata	Std	0603
J1, J2, J3, J4, J5, J6, J7, J8	8	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	OST	ED555/2DS	0.27 x 0.25 inch
L1	1	2.2uH	Inductor, Power, 5.5A, 14milliohm	Coilcraft	MSS1260-222NL_	0.484 x 0.484 inch
L2	1	3.3uH	Inductor, SMT Power, ±20%	Coilcraft	MOS6020-332ML	0.240 x 0.268 inch
L3, L5, L6, L7	4	2.2uH	Inductor, SMT Power, ±20%	Coilcraft	MOS6020-222ML	0.240 x 0.268 inch
L4	1	2..2uH	Inductor, SMT Power, ±20%	Coilcraft	MOS6020-222ML	0.240 x 0.268 inch
R1, R5, R6, R7, R9, R11, R12, R15, R17, R18, R20, R26	12	22.1K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R10	1	12.7K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R13, R19	2	6.81K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R14, R25	2	0	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R16	1	30.1K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R2	1	124K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603

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R21, R23	2	Open	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R3	1	73.2K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R4	1	100K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
R8	1	49.9K	Resistor, Chip, 1/16W, 1%	Vishay	Std	0603
TP1, TP6, TP9, TP11, TP13, TP15, TP17	7	5010	Test Point, Red, Thru Hole	Keystone	5010	0.125 x 0.125 inch
TP2, TP8, TP10, TP12, TP14, TP16, TP18	7	5011	Test Point, Black, Thru Hole	Keystone	5011	0.125 x 0.125 inch
TP3, TP7	2	5000	Test Point, Red, Thru Hole Color Keyed	Keystone	5000	0.100 x 0.100 inch
TP5	1	5001	Test Point, Black, Thru Hole Color Keyed	Keystone	5001	0.100 x 0.100 inch
U1	1	TPS54425PWP	IC, 4-A Output Single Sync. Step-Down Switcher with Inte	Texas Instruments	TPS54425PWP	HTSSOP-14
U2, U3, U4, U5, U6	5	TPS54227DDA	IC, Sync.Step-Down Converter,	TI	TPS54227DDA	SO8[DDA]
U7	1	TPS54327DDA	IC, Sync.Step-Down Converter,	TI	TPS54327DDA	SO8[DDA]

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